



Product Change Notification

Change Notification #: 115965 - 01

Change Title: Select Intel® SSD 600p Series, Intel® SSD Pro 6000p Series, Intel® SSD DC 3100p Series, Intel® SSD E 6000p Series products
PCN 115965-01, Label, Label updates
Reason for Revision: Updating “Description of Change to Customer” field, updating Label images and adding Embedded label images for (E 6000P)

Date of Publication: July 19, 2018

Key Characteristics of the Change:

Label

Forecasted Key Milestones:

Date Customer Must be Ready to Receive Post-Conversion Material:	December 15, 2017
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Description of Change to the Customer:

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The Intel® 600p, Pro 6000p, E 6000p, and DC 3100p Series SKUs listed in the Products Affected Table below will undergo the following label changes.

- Label resizing from 55 mm X13 mm to 62.5 mm X 13 mm to accommodate for adding additional regulatory logos
- Adding Ukraine and Morocco logos
- Replacing circle 20 with circle e regulatory logo
- Rearrange label layout

OPAL Products (6000P):

Before (Label Size Before: 55x13)



After (Label Size After: 62.5x13)



Non-OPAL Products (600P):

Before (Label Size Before: 55x13)



After (Label Size After: 62.5x13)



Embedded Products (E 6000P):

Before (Label Size Before: 55x13)



After (Label Size After: 62.5x13)



Data Center Products (DC P3100):

Before (Label Size Before: 55x13)



After (Label Size After: 62.5x13)



Customer Impact of Change and Recommended Action:

There is no change to the Form, Fit, or Function of the product. The change is only to the labels used in packaging.

Customers should be aware of the changes to the label and take appropriate actions to accommodate the changes and avoid impact to their process.

Milestone dates are estimates and subject to change based on business and operational conditions.

Please contact your local Intel Field Sales Rep if you have any further questions about these changes.

Products Affected / Intel Ordering Codes:

Marketing Name	Product Code	MM#
Intel® SSD Pro 6000p Series (128GB, M.2 80mm PCIe 3.0 x4, 3D1, TLC) Reseller Single Pack	SSDPEKKF128G7X1	950352
Intel® SSD Pro 6000p Series (256GB, M.2 80mm PCIe 3.0 x4, 3D1, TLC) Reseller Single Pack	SSDPEKKF256G7X1	950353
Intel® SSD Pro 6000p Series (512GB, M.2 80mm PCIe 3.0 x4, 3D1, TLC) Reseller Single Pack	SSDPEKKF512G7X1	950354
Intel® SSD Pro 6000p Series (1.0TB, M.2 80mm PCIe 3.0 x4, 3D1, TLC) Reseller Single Pack	SSDPEKKF010T7X1	950355
Intel® SSD 600p Series (128GB, M.2 80mm PCIe 3.0 x4, 3D1, TLC) Reseller Single Pack	SSDPEKKW128G7X1	950358
Intel® SSD 600p Series (256GB, M.2 80mm PCIe 3.0 x4, 3D1, TLC) Reseller Single Pack	SSDPEKKW256G7X1	950359
Intel® SSD 600p Series (512GB, M.2 80mm PCIe 3.0 x4, 3D1, TLC) Reseller Single Pack	SSDPEKKW512G7X1	950360
Intel® SSD 600p Series (1.0TB, M.2 80mm PCIe 3.0 x4, 3D1, TLC) Reseller Single Pack	SSDPEKKW010T7X1	950361
Intel® SSD E 6000p Series (128GB, M.2 80mm PCIe 3.0 x4, 3D1, TLC) Embedded No OPAL Single Pack	SSDPEKKR128G7XN	950525
Intel® SSD E 6000p Series (256GB, M.2 80mm PCIe 3.0 x4, 3D1, TLC) Embedded No OPAL Single Pack	SSDPEKKR256G7XN	950526
Intel® SSD DC P3100 Series (128GB, M.2 80mm PCIe 3.0 x4, 3D1, TLC) Generic Single Pack	SSDPEKKA128G701	953765
Intel® SSD DC P3100 Series (256GB, M.2 80mm PCIe 3.0 x4, 3D1, TLC) Generic Single Pack	SSDPEKKA256G701	953766
Intel® SSD DC P3100 Series (512GB, M.2 80mm PCIe 3.0 x4, 3D1, TLC) Generic Single Pack	SSDPEKKA512G701	953767
Intel® SSD DC P3100 Series (360GB, M.2 80mm PCIe 3.0 x4, 3D1, TLC) Generic Single Pack	SSDPEKKA360G701	953768
Intel® SSD DC P3100 Series (1.0TB, M.2 80mm PCIe 3.0 x4, 3D1, TLC) Generic Single Pack	SSDPEKKA010T701	953769
Intel® SSD 600p Series (128GB, M.2 80mm PCIe 3.0 x4, 3D1, TLC) Generic 100 Pack	SSDPEKKW128G7X3	954499
Intel® SSD 600p Series (256GB, M.2 80mm PCIe 3.0 x4, 3D1, TLC) Generic 100 Pack	SSDPEKKW256G7X3	954500
Intel® SSD 600p Series (512GB, M.2 80mm PCIe 3.0 x4, 3D1, TLC) Generic 100 Pack	SSDPEKKW512G7X3	954501
Intel® SSD Pro 6000p Series (128GB, M.2 80mm PCIe 3.0 x4, 3D1, TLC) 10 Pack	SSDPEKKW128G7XT	956991
Intel® SSD 600p Series (256GB, M.2 80mm PCIe 3.0 x4, 3D1, TLC) 10 Pack	SSDPEKKW256G7XT	956992
Intel® SSD 600p Series (512GB, M.2 80mm PCIe 3.0 x4, 3D1, TLC) 10 Pack	SSDPEKKW512G7XT	956993
Intel® SSD 600p Series (1.0TB, M.2 80mm PCIe 3.0 x4, 3D1, TLC) 5 Pack	SSDPEKKW010T7X5	956994

PCN Revision History:

Date of Revision:

November 28, 2017

July 19, 2018

Revision Number:

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01

Reason:

Originally Published PCN

Updating “Description of Change to Customer” field, updating Label images and adding Embedded label images (E 6000P)



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